

# Bonding Source Hot Plates

The microelectronics and RF/Microwave assemblers' choice for pre-tacking epoxy film, epoxy curing, SMD reflow, rework, and wire bonding base heat.

# BS-2.5-3

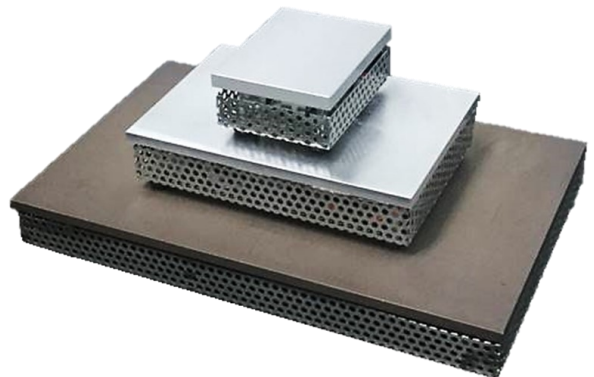


## Hot Plate System Features

- Smallest industrial hot plate footprint
- Low-profile (1.4" Ht.) hot plate conveniently fits beneath microscopes and wire bond stages
- Modular design: plates can be used interchangeably with Bonding Source digital PID controllers and cable assemblies
- Hot plates are matched in height to 1.4" and available in the following sizes: 10.5"x6.5", 6"x4", and 3"x2.5"
- Digital controller ensures process consistency
- Rapid heating and recovery

## Technical Specifications

<u>Overall Dimensions</u>	
• Length	3.125 in
• Width	2.5 in
• Height	1.4 in
Heated Area	3.125in x 2.5in
Weight	0.4 lbs
Max. Temperature	300 °C
Plate Material	Aluminum (Anodized)
Power Req.	120VAC 60Hz
Thermocouple Cable Length	3 ft
Power Cord Length	6 ft



**bonding source**

Bonding Source  
603.595.9600  
One Perimeter Road  
Manchester NH 03103  
[www.bondingsource.com](http://www.bondingsource.com)